

DATE: 08/13/2004

cosmo

# KL-670CGX

NO. 61L40010 REV.

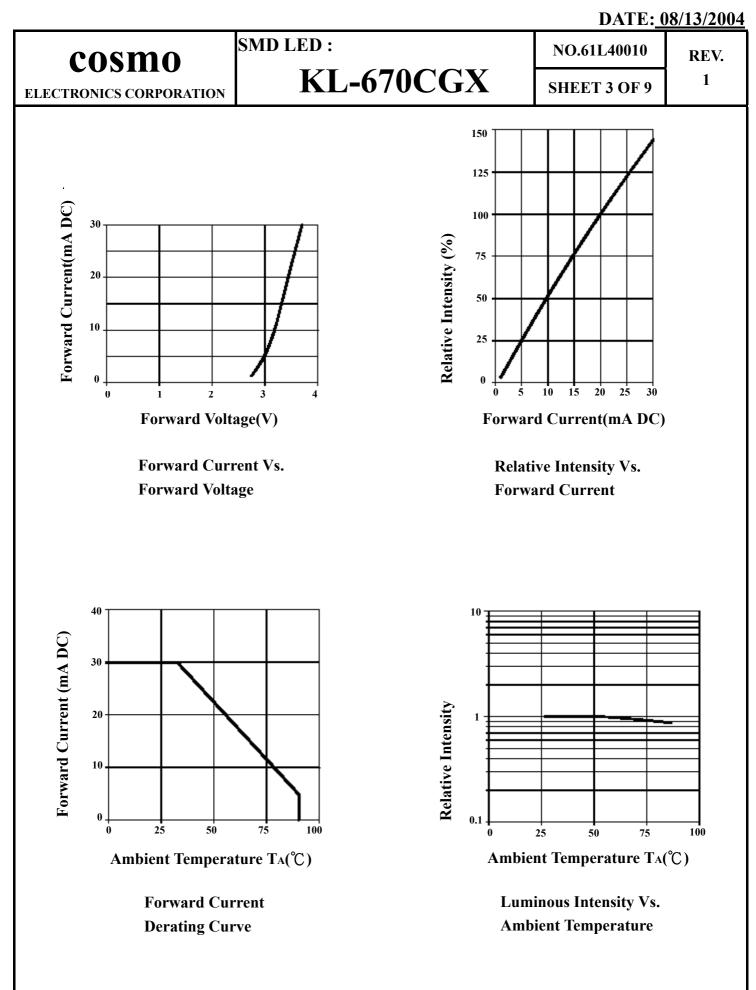
1 SHEET 2 OF 9

**ELECTRONICS CORPORATION** 

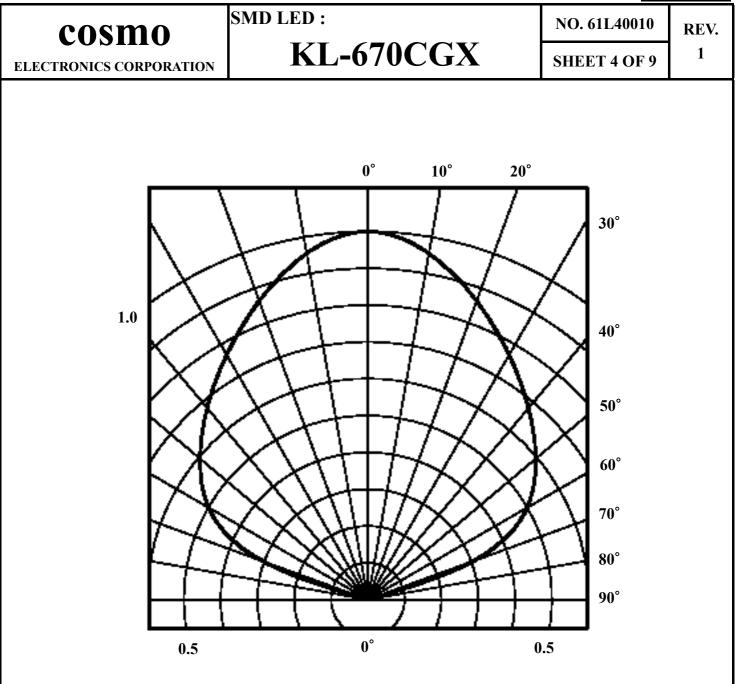
Absolute maximum ratings (TA=25°C)		T2G Green (InGaN)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current(Peak)	IFP	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	105	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	°C
Storage temperature	Тѕт	-40~+85	°C
LED DISPLAYS:			
<b>Operating temperature</b>	ТА	-40~+85	°C
Storage temperature	Тятс	-40~+85	°C

Operating characteristics (TA=25°C)		T2G Green (InGaN)	Unit
Forward voltage(typ.) IF=20mA	VF	3.5	V
Forward voltage(max.) IF=20mA	VF	4.0	V
Reverse current(max.) V <sub>R</sub> =5V	Ir	10	uA
Wavelength at dominant emission(typ.) IF=20mA	λο	525	nm
Wavelength at peak emission(typ.) IF=20mA	λр	523	nm
IF=20mA Spectral line half-width IF=20mA	$\Delta$ $\lambda$	36	nm
Capacitance VF=0V,f=1MHz	С	20	pF

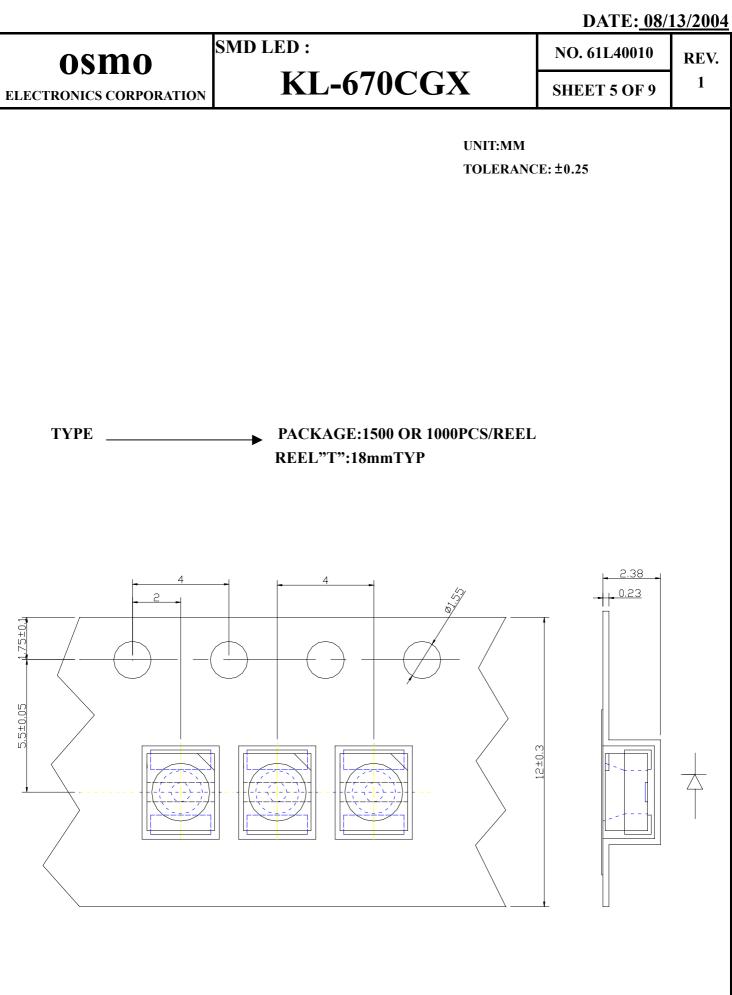
#### SMD LED :

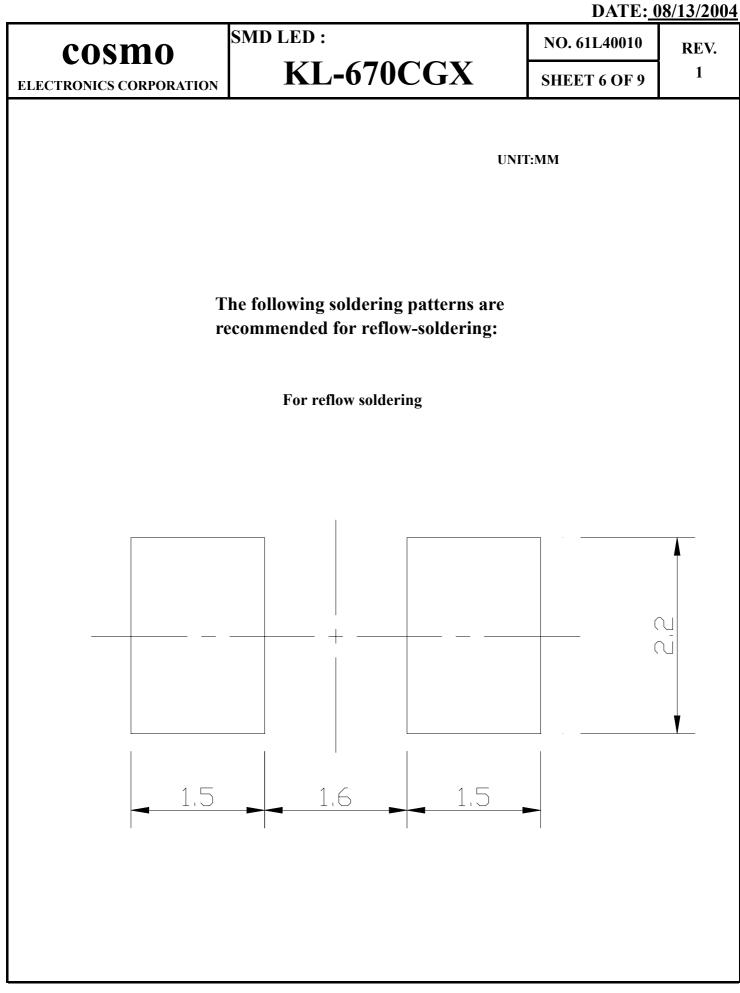


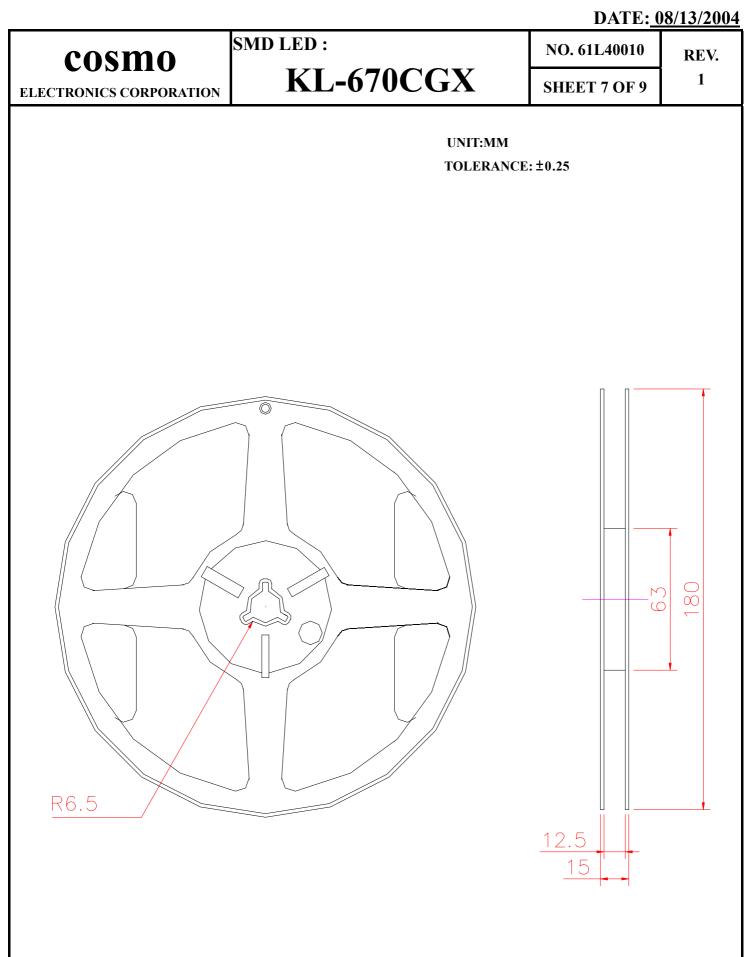
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View Angle 2 ∂1/2=120°







#### DATE: 08/13/2004 **SMD LED :** NO. 61L40010 cosmo REV. **KL-670CGX** 1 **SHEET 8 OF 9 ELECTRONICS CORPORATION SOLDERING SMT REFLOW SOLDERING INSTRUCTIONS** 10 sec MAX Temp (°C) TEMPERATURE 230 4° C/sec max 140~160°C $4^{\circ}$ C/sec max Time 35sec MAX -60~120sec-SOLDERING INSRTUCTIONS **DIP AND WAVE SOLDERING** IRON SOLDERING(WITH 1.5mm IRON TIP) **TYPES TEMPERATURE OF** MAXLMUM DISTANCE FORM **TEMPERATURE OF** MAXLMUM DISTANCE FROM THE SOLDERING SOLDERING SOLDER JOINT SOLDERING SOLDERING SOLDER JOINT BATH TIME **TO CASE** IRON TIME TO CASE ≦**260**°C 3S >2mm **≦260**°C 3S >2mm LEDS ≦**260**°C 5S >4mm ≦**260**°C **5**S >4mm >2mm DISPLAYS ≤**260**°C 3S ≤**260**°C 3S >2mm ≦**260**°C 3S >2mm ≦**260**°C 3S >2mm DISPLAYS

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REV.

1

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ELECTRONICS CORPORATION

SMD LED :

KL-670CGX

#### **SMD HANDLING AND APPLICATION PRECAUTIONS**

#### STORAGE

(1.1)It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature:  $5^{\circ}C \sim 30^{\circ}C$  (41°F ~ 86°F)

(1.2)Shelf life in sealed bag: 12 month at  $<5^{\circ}C \sim 30^{\circ}C$  and <30%RH. After the package is opened, the products should be used within 72hrs. Or they should be kept at  $\leq 20\%$ RH in zip -locked sealed bags.

#### DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a)  $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b)  $100\pm3^{\circ}C$  x (45min~1hr), loose packing type, or
- (c)  $130\pm3^{\circ}C$  x (15~30min), loose packing type

#### **ELECTRIC STATIC DISCHARGE(ESD) PROTECTION**

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.